

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicants: M. ISHIKAWARA, et al.  
Application No.: 10/526,008  
Filed: FEBRUARY 25, 2005  
For: METHOD OF MANUFACTURING EPOXY RESIN  
COMPOSITION FOR SEMICONDUCTOR ENCAPSULATING  
Group AU: 4111  
Examiner: David N. Brown II  
Confirm. No: 1178

**AMENDMENT**

**Mail Stop: AMEND - FEE**  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

September 8, 2008

Sir:

In response to the Office Action mailed May 6, 2008, the period for response having been extended for one (1) month by the attached Petition for Extension of Time, please amend the above-identified application as listed in the following, and as set forth on the following pages:

AMENDMENTS TO THE CLAIMS; and

REMARKS are included following the amendments.